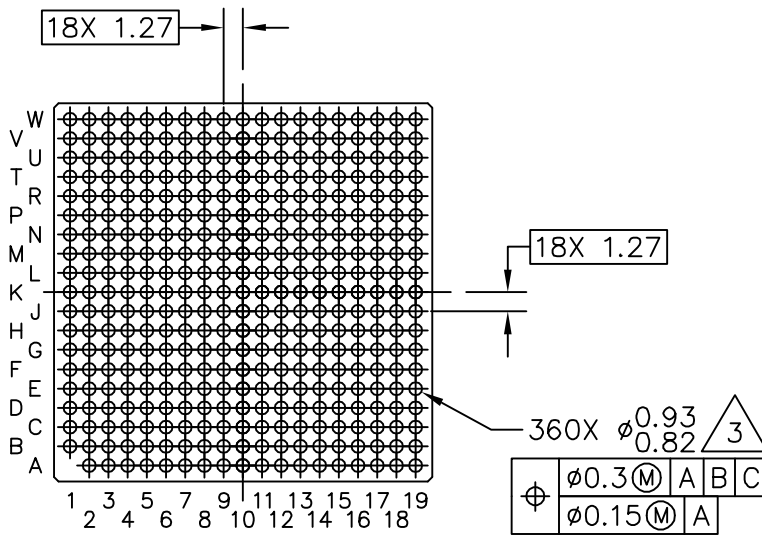
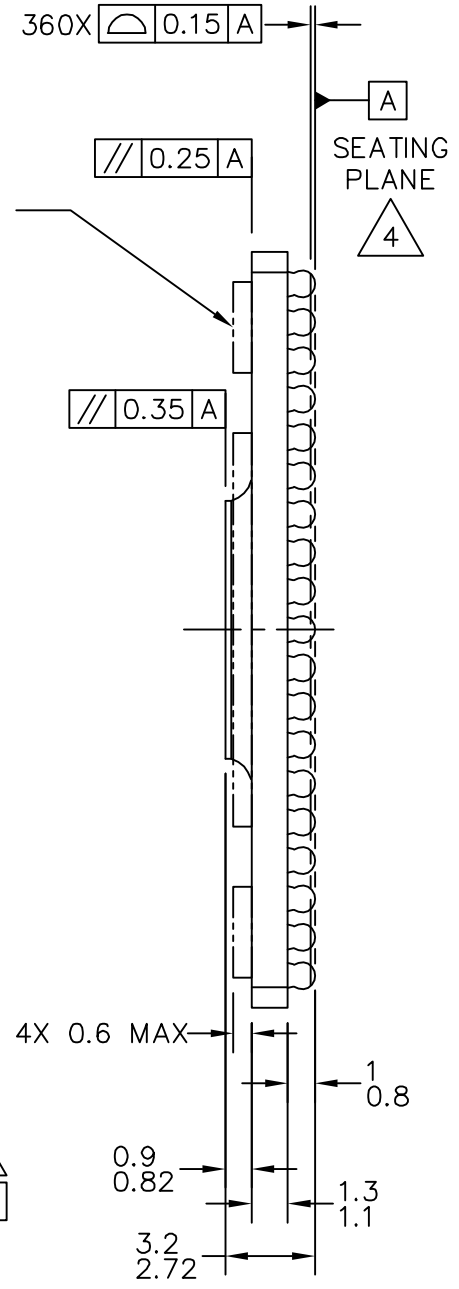


TOP VIEW



BOTTOM VIEW



SIDE VIEW

© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 360 I/O FC CBGA, 25 X 25 PKG, 1.27MM PITCH, WITH CAP ZONES	DOCUMENT NO: 98ARE10530D	REV: B
	STANDARD: JEDEC M0-156 ABJ	
	SOT1603-1	17 DEC 2015



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

2. ALL DIMENSIONS IN MILLIMETERS.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

6. CAUTION MUST BE TAKEN NOT TO SHORT EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 360 I/O FC CBGA, 25 X 25 PKG, 1.27MM PITCH, WITH CAP ZONES		DOCUMENT NO: 98ARE10530D REV: B	
		STANDARD: JEDEC M0-156 ABJ	
		S0T1603-1	17 DEC 2015